

# 54F/74F240•54F/74F241•54F/74F244 Octal Buffers/Line Drivers with TRI-STATE® Outputs

## **General Description**

The 'F240, 'F241 and 'F244 are octal buffers and line drivers designed to be employed as memory and address drivers, clock drivers and bus-oriented transmitters/receivers which provide improved PC and board density.

#### **Features**

- TRI-STATE outputs drive bus lines or buffer memory address registers
- Outputs sink 64 mA (48 mA mil)
- 12 mA source current
- Input clamp diodes limit high-speed termination effects
- Guaranteed 4000V minimum ESD protection

Commercial	Military	Package Number	Package Description
74F240PC		N20A	20-Lead (0.300" Wide) Molded Dual-In-Line
	54F240DM (Note 2)	J20A	20-Lead Ceramic Dual-In-Line
74F240SC (Note 1)		M20B	20-Lead (0.300" Wide) Molded Small Outline, JEDEC
74F240SJ (Note 1)		M20D	20-Lead (0.300" Wide) Molded Small Outline, EIAJ
	54F240FM (Note 2)	W20A	20-Lead Cerpack
	54F240LM (Note 2)	E20A	20-Lead Ceramic Leadless Chip Carrier, Type C
74F241PC		N20A	20-Lead (0.300" Wide) Molded Dual-In-Line
	54F241DM (Note 2)	J20A	20-Lead Ceramic Dual-In-Line
74F241SC (Note 1)		M20B	20-Lead (0.300" Wide) Molded Small Outline, JEDEC
74F241SJ (Note 1)		M20D	20-Lead (0.300" Wide) Molded Small Outline, EIAJ
	54F241FM (Note 2)	W20A	20-Lead Cerpack
	54F241LM (Note 2)	E20A	20-Lead Ceramic Leadless Chip Carrier, Type C
74F244PC		N20A	20-Lead (0.300" Wide) Molded Dual-In-Line
	54F244DM (Note 2)	J20A	20-Lead Ceramic Dual-In-Line
74F244SC (Note 1)		M20B	20-Lead (0.300" Wide) Molded Small Outline, JEDEC
74F244SJ (Note 1)		M20D	20-Lead (0.300" Wide) Molded Small Outline, EIAJ
74F244MSA (Note 1)		MSA20	20-Lead Molded Shrink Small Outline, EIAJ Type II
	54F244FM (Note 2)	W20A	20-Lead Cerpack
	54F244LM (Note 2)	E20A	20-Lead Ceramic Leadless Chip Carrier, Type C

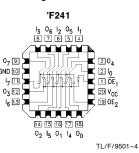
Note 1: Devices also available in 13" reel. Use Suffix = SCX, SJX and MSAX.

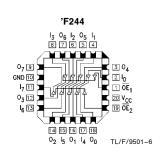
Note 2: Military grade device with environmental and burn-in processing. Use suffix = DMQB, FMQB and LMQB.

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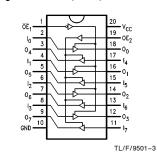
# **Connection Diagrams** Pin Assignment for LCC 'F240 $\begin{bmatrix} 1_3 & \bar{0}_6 & 1_2 & \bar{0}_5 & 1_1 \\ 8 & 7 & 6 & 5 & 4 \end{bmatrix}$ 3 Ō<sub>4</sub> 2 l<sub>0</sub> 1 ŌĒ<sub>1</sub> 20 V<sub>CC</sub> 19 ŌĒ<sub>2</sub> Ō<sub>7</sub> 9 GND 10 I<sub>7</sub> 11 O<sub>3</sub> 12 I<sub>6</sub> 13 0<sub>7</sub> 9 GND 10 1<sub>7</sub> 11 0<sub>3</sub> 12 14 15 16 17 18 $\bar{\mathrm{O}}_{2}$ I<sub>5</sub> $\bar{\mathrm{O}}_{1}$ I<sub>4</sub> $\bar{\mathrm{O}}_{0}$ TL/F/9501-2 19 VCC OE2 18 00 17 I<sub>4</sub> 16 ō, 13 12

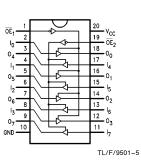
TL/F/9501-1



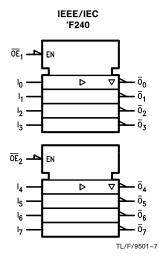


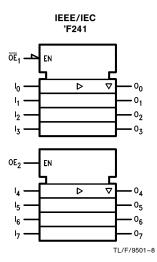
Pin Assignment for DIP, SOIC, SSOP and Flatpak

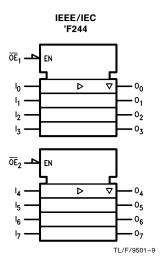




## **Logic Symbols**







# Unit Loading/Fan Out

		54F/74F				
Pin Names	Description	U.L. HIGH/LOW	Input I <sub>IH</sub> /I <sub>IL</sub> Output I <sub>OH</sub> /I <sub>OL</sub>			
$\overline{OE}_1, \overline{OE}_2$	TRI-STATE Output Enable Input (Active LOW)	1.0/1.667	20 μA/-1 mA			
OE <sub>2</sub>	TRI-STATE Output Enable Input (Active HIGH)	1.0/1.667	20 μA/ – 1 mA			
I <sub>0</sub> -I <sub>7</sub>	Inputs ('F240)	1.0/1.667*	20 μA/-1 mA			
I <sub>0</sub> -I <sub>7</sub>	Inputs ('F241, 'F244)	1.0/2.667*	20 μA/ – 1.6 mA			
$\overline{O}_0 - \overline{O}_7$ , $O_0 - O_7$	Outputs	600/106.6 (80)	-12 mA/64 mA (48 mA)			

<sup>\*</sup>Worst-case 'F240 enabled; 'F241, 'F244 disabled

## **Truth Tables**

#### 'F240

ŌE <sub>1</sub>	D <sub>1n</sub>	O <sub>1n</sub>	OE <sub>2</sub>	D <sub>2n</sub>	O <sub>2n</sub>
Н	х	Z	Н	Х	Z
L	Н	L	L	Н	L
L	L	Н	L	L	Н

#### 'F241

ŌE <sub>1</sub>	D <sub>1n</sub>	O <sub>1n</sub>	OE <sub>2</sub>	D <sub>2n</sub>	O <sub>2n</sub>
Н	Х	Z	L	Х	Z
L	Н	Н	Н	Н	Н
L	L	L	Н	L	L

#### 'F244

OE <sub>1</sub>	D <sub>1n</sub>	O <sub>1n</sub> $\overline{\text{OE}}_2$		D <sub>2n</sub>	O <sub>2n</sub>
Н	Х	Z	Н	Х	Z
L	Н	Н	L	Н	Н
l L	l L	L	L	L	L

- H = HIGH Voltage Level
  L = LOW Voltage Level
  X = Immaterial
  Z = High Impedance

#### **Absolute Maximum Ratings** (Note 1)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

-65°C to +150°C Storage Temperature Ambient Temperature under Bias -55°C to +125°C Junction Temperature under Bias  $-55^{\circ}$ C to  $+175^{\circ}$ C  $-55^{\circ}\text{C}$  to  $+150^{\circ}\text{C}$ Plastic

 $V_{CC}$  Pin Potential to

Ground Pin -0.5V to +7.0VInput Voltage (Note 2) -0.5V to +7.0VInput Current (Note 2) -30~mA to +5.0~mA

Voltage Applied to Output

in HIGH State (with V<sub>CC</sub> = 0V)

 $-0.5\mbox{V}$  to  $\mbox{V}_{\mbox{CC}}$ Standard Output TRI-STATE Output -0.5V to +5.5V

Current Applied to Output in LOW State (Max) twice the rated  $I_{OL}$  (mA) ESD Last Passing Voltage (Min)

Note 1: Absolute maximum ratings are values beyond which the device may be damaged or have its useful life impaired. Functional operation under

these conditions is not implied.

Note 2: Either voltage limit or current limit is sufficient to protect inputs.

## **Recommended Operating Conditions**

Free Air Ambient Temperature

Military  $-55^{\circ}$ C to  $+125^{\circ}$ C Commercial  $0^{\circ}$ C to  $+70^{\circ}$ C

Supply Voltage

Military +4.5V to +5.5VCommercial +4.5V to +5.5V

#### **DC Electrical Characteristics**

Symbol	Parame	ator.		54F/74F	•	Units	V	Conditions		
Syllibol	Parame	eter	Min	Тур	Max	Ullits	V <sub>CC</sub>	Conditions		
V <sub>IH</sub>	Input HIGH Voltage		2.0			٧		Recognized as a HIGH Signal		
$V_{IL}$	Input LOW Voltage				0.8	٧		Recognized as a LOW Signal		
$V_{CD}$	Input Clamp Diode V	/oltage			-1.2	٧	Min	$I_{\text{IN}} = -18 \text{ mA}$		
V <sub>OH</sub>	Output HIGH Voltage	54F 10% V <sub>CC</sub> 54F 10% V <sub>CC</sub> 74F 10% V <sub>CC</sub> 74F 10% V <sub>CC</sub> 74F 5% V <sub>CC</sub>	2.4 2.0 2.4 2.0 2.7			<b>V</b>	Min	$\begin{split} I_{OH} &= -3 \text{ mA} \\ I_{OH} &= -12 \text{ mA} \\ I_{OH} &= -3 \text{ mA} \\ I_{OH} &= -15 \text{ mA} \\ I_{OH} &= -3 \text{ mA} \end{split}$		
$V_{OL}$	Output LOW Voltage	54F 10% V <sub>CC</sub> 74F 10% V <sub>CC</sub>			0.55 0.55	٧	Min	$I_{OL} = 48 \text{ mA}$ $I_{OL} = 64 \text{ mA}$		
I <sub>IH</sub>	Input HIGH Current	54F 74F			20.0 5.0	μΑ	Max	$V_{\text{IN}} = 2.7V$		
I <sub>BVI</sub>	Input HIGH Current Breakdown Test	54F 74F			100 7.0	μΑ	Max	$V_{IN} = 7.0V$		
I <sub>CEX</sub>	Output HIGH Leakage Current	54F 74F			250 50	μΑ	Max	$V_{OUT} = V_{CC}$		
$V_{\text{ID}}$	Input Leakage Test	74F	4.75			٧	0.0	$I_{\text{ID}} = 1.9  \mu\text{A}$ All Other Pins Grounded		
I <sub>OD</sub>	Output Leakage Circuit Current	74F			3.75	μΑ	0.0	V <sub>IOD</sub> = 150 mV All Other Pins Grounded		
I <sub>IL</sub>	Input LOW Current				-1.0 -1.6	mA	Max	$V_{IN} = 0.5V (\overline{OE}_1, \overline{OE}_2, OE_2, D_n (F240))$ $V_{IN} = 0.5V (D_n (F241, F244))$		
l <sub>OZH</sub>	Output Leakage Cur	rent			50	μΑ	Max	$V_{OUT} = 2.7V$		
l <sub>OZL</sub>	Output Leakage Cur	rent			-50	μΑ	Max	$V_{OUT} = 0.5V$		
los	Output Short-Circuit	Current	-100		-225	mA	Max	$V_{OUT} = 0V$		
I <sub>ZZ</sub>	Bus Drainage Test				500	μΑ	0.0V	V <sub>OUT</sub> = 5.25V		

4000V

DC Electrical Characteristics	(Continued)
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Symbol	Parameter		54F/74F			v <sub>cc</sub>	Conditions	
	Tarameter	Min	Тур	Max	Units	•66	Conditions	
Icch	Power Supply Current ('F240)		19	29	mA	Max	V <sub>O</sub> = HIGH	
ICCL	Power Supply Current ('F240)		50	75	mA	Max	$V_O = LOW$	
I <sub>CCZ</sub>	Power Supply Current ('F240)		42	63	mA	Max	V <sub>O</sub> = HIGH Z	
Іссн	Power Supply Current ('F241, 'F244)		40	60	mA	Max	V <sub>O</sub> = HIGH	
ICCL	Power Supply Current ('F241, 'F244)		60	90	mA	Max	$V_O = LOW$	
lccz	Power Supply Current ('F241, 'F244)		60	90	mA	Max	V <sub>O</sub> = HIGH Z	

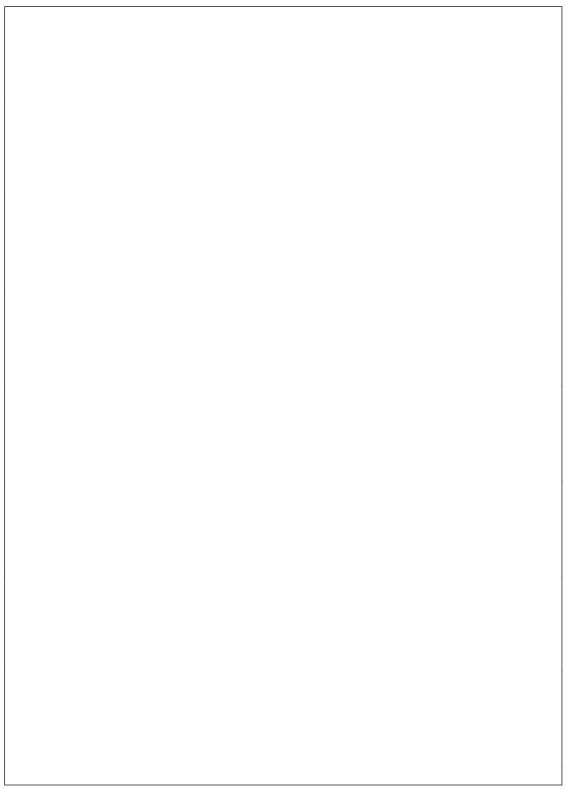
#### **AC Electrical Characteristics**

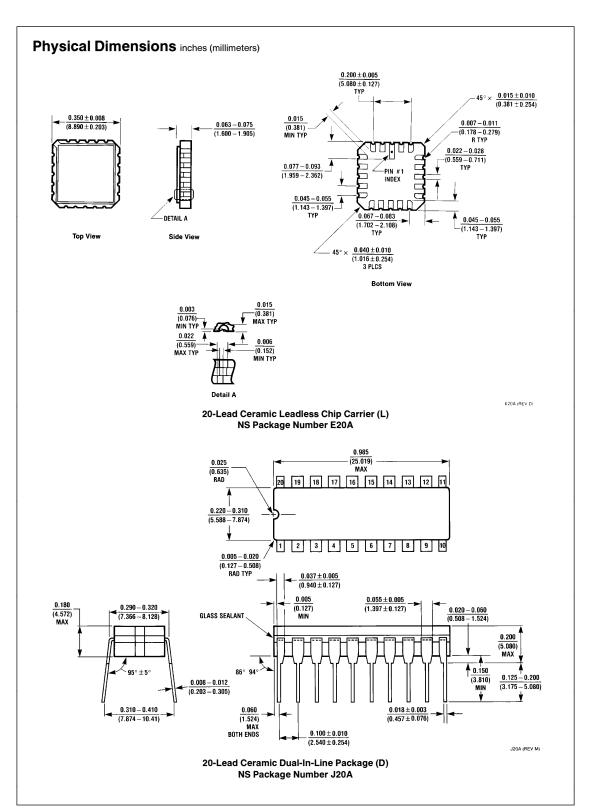
			74F		5	4F	7-	4F	
Symbol	Parameter	$T_{A}=+25^{\circ}C$ $V_{CC}=+5.0V$ $C_{L}=50\text{pF}$			T <sub>A</sub> , V <sub>CC</sub> = Mil C <sub>L</sub> = 50 pF		T <sub>A</sub> , V <sub>CC</sub> = Com C <sub>L</sub> = 50 pF		Units
		Min	Тур	Max	Min	Max	Min	Max	
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation Delay Data to Output ('F240)	3.0 2.0	5.1 3.5	7.0 4.7	3.0 2.0	9.0 6.0	3.0 2.0	8.0 5.7	ns
t <sub>PZH</sub>	Output Enable Time ('F240)	2.0 4.0	3.5 6.9	4.7 9.0	2.0 4.0	6.5 10.5	2.0 4.0	5.7 10.0	- ns
t <sub>PHZ</sub>	Output Disable Time ('F240)	2.0 2.0	4.0 6.0	5.3 8.0	2.0 2.0	6.5 12.5	2.0 2.0	6.3 9.5	113
t <sub>PLH</sub>	Propagation Delay Data to Output ('F241, 'F244)	2.5 2.5	4.0 4.0	5.2 5.2	2.0 2.0	6.5 7.0	2.5 2.5	6.2 6.5	ns
t <sub>PZH</sub>	Output Enable Time ('F241, 'F244)	2.0 2.0	4.3 5.4	5.7 7.0	2.0 2.0	7.0 8.5	2.0 2.0	6.7 8.0	ns
t <sub>PHZ</sub>	Output Disable Time ('F241, 'F244)	2.0 2.0	4.5 4.5	6.0 6.0	2.0 2.0	7.0 7.5	2.0 2.0	7.0 7.0	113

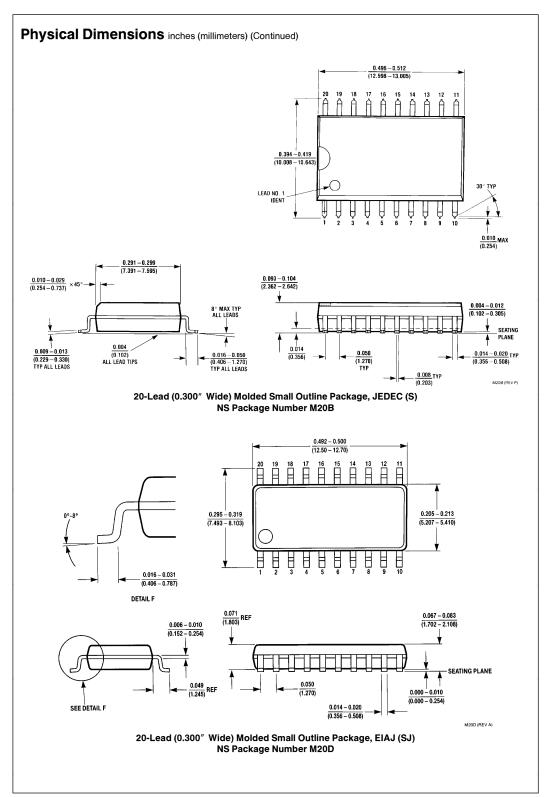
## **Ordering Information**

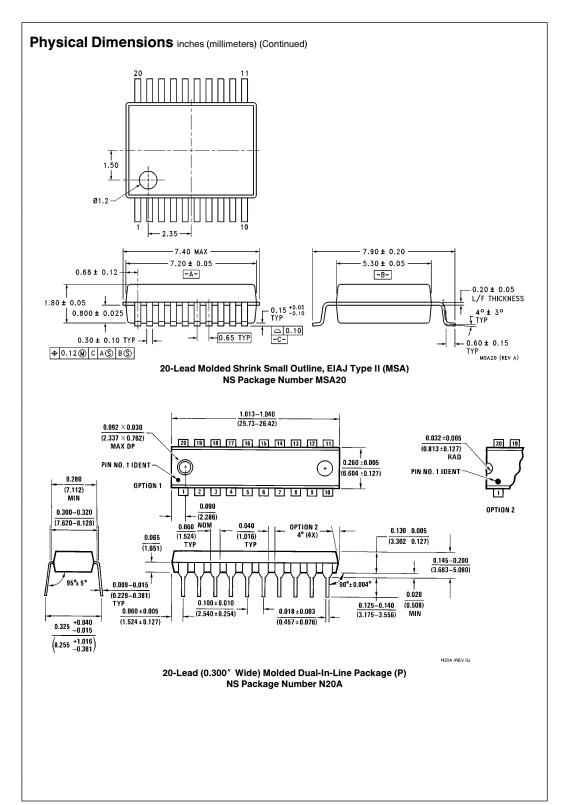
The device number is used to form part of a simplified purchasing code where the package type and temperature range are defined as follows:

<u>74F</u> 240/241/244\* - Special Variations Temperature Range Family -74F = Commercia QB = Military grade device with 54F = Military environmental and burn-in processing
X = devices shipped in 13" reel Device Type Package Code -Temperature Range P = Plastic DIP C = Commercial (0°C to +70°C) M = Military (-55°C to +125°C) D = Ceramic DIPF = Flatpak NOTE: L = Leadless Chip Carrier (LCC) S = Small Outline SOIC JEDEC Not required for MSA package code \*MSA = Shrink Small Outline Package (EIAJ SSOP) ('244 only)
SJ = Small Outline SOIC EIAJ

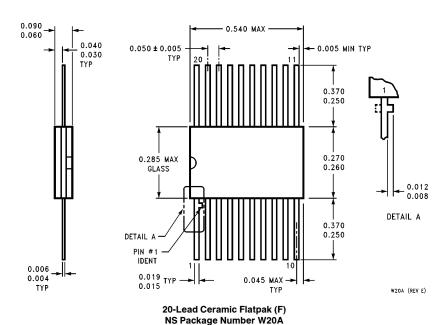








## Physical Dimensions inches (millimeters) (Continued)



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